

# What MSP offers

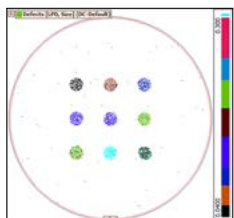
## Particle Deposit Attributes

Attribute	Available Options or Ranges
Particle Type / Material	<ul style="list-style-type: none"> <li>PSL Size Standards</li> <li>SiO<sub>2</sub> Size Standards</li> <li>MSP Process Particles™ Suspensions<sup>2</sup> (AlF<sub>3</sub>, Al<sub>2</sub>O<sub>3</sub>, Ni, Ru, Si, Si<sub>3</sub>N<sub>4</sub>, SiO<sub>2</sub>, Sn, Ti, Ta, TiN, TiO<sub>2</sub>, W, Y<sub>2</sub>O<sub>3</sub>)</li> </ul>
Particle Size <sup>3</sup>	10 nm – 20 μm
Standard Particle Count	Minimum 400 particles per deposit
Pattern Width	Typically 10-30 mm. Range of Pattern Width (e.g., Spot Diameter) is dependent on Particle Size.

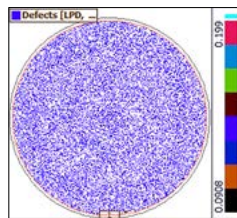
<sup>2</sup>Restrictions on particle size apply to all Process Particles™ Suspensions.

<sup>3</sup>Only PSL Spheres are available up to 20 μm. SiO<sub>2</sub> Spheres are available up to 16 μm.

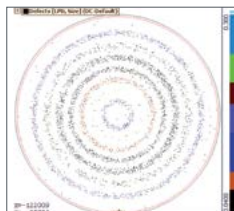
## Pattern Type



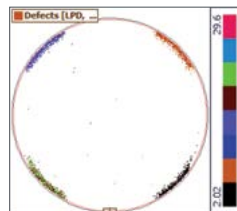
Spot Deposit



Full Deposition



Ring Deposition



Edge and Arc Depositions

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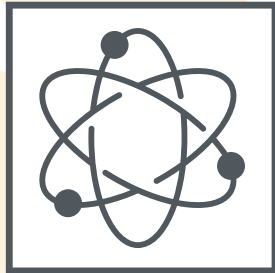
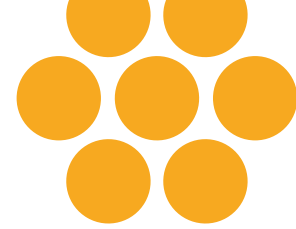


MSP - Visit our website [www.tsi.com/msp](http://www.tsi.com/msp) for more information.

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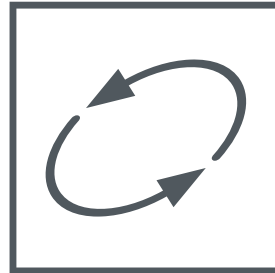


# MSP Has Programs Developed For Your Needs



## Dev-Dep™

- Developmental deposition
- Designed around fast-paced R&D environment
- Accelerates product and process development
- Totally customized leading-edge solution
- Consult with industry experts



## Qual-Dep™

- Qualification deposition
- Customer specific part number
  - Simplified purchasing process
  - Defined specification and consistent deliverable
  - Advantageous pricing
  - Shorter lead-times
- Developed for repetitive needs
- Shipped with inspection tool for Fab qualification

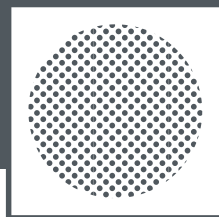


## Metrology Department

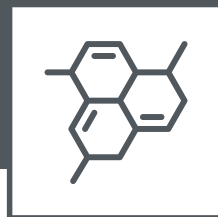
- Provide end user with state-of-the-art inspection tool
- Trusted source
- Same inspection tool with high quality, consistent qualification substrate



Introduction of Moore's law, 1965



Beginning of submicron, 1985



Airborne molecular contamination issue, 1990s



Need to identify "killer" particle contaminants has increased



EUV (Extreme Ultraviolet) wave of the future